



# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Sung Soon Park, Sang Jae Jang, Choon Heung Lee,  
Seon Goo Lee, Eun Sook Sohn, Sung Su Park

Assignee: Amkor Technology, Inc.

Title: SEMICONDUCTOR PACKAGE STRUCTURE REDUCING WARPAGE  
AND MANUFACTURING METHOD THEREOF

Serial No.: 10/672,886 Filed: September 26, 2003

Examiner: Tuan H. Nguyen Group Art 2813  
Unit:

Docket No.: GK0017

Chandler, AZ

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## **REVOCATION AND SUBSTITUTION OF POWER OF ATTORNEY UNDER 37 C.F.R. §1.36**

Sir:

Pursuant to 37 C.F.R. §1.36, Amkor Technology, Inc., the record owner of the above-identified patent application, revokes all previous powers of attorney and hereby appoints the following attorneys and/or agents assigned to the below Customer Number to prosecute this application and transact all business in the U.S. Patent and Trademark Office connected therewith:

Customer Number 23513

Please direct all correspondence and telephone calls concerning this application to:

Serge J. Hodgson  
GUNNISON, MCKAY & HODGSON, L.L.P.  
1900 Garden Road, Suite 220  
Monterey, CA 93940  
Telephone: (831) 655-0880  
Facsimile: (831) 655-0888.

GUNNISON, MCKAY &  
HODGSON, L.L.P.  
1900 Garden Road, Suite 220  
Monterey, CA 93940  
(831) 655-0880  
Fax: (831) 655-0888

The undersigned representative of the above-identified assignee certifies that the above-identified assignee is the assignee of the entire right, title and interest in the above-identified patent application by virtue of a chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee.

An Assignment from the inventor(s) of the patent application to Amkor Technology, Inc. was recorded in the U.S. Patent and Trademark Office at Reel/Frame 014561/0233.

The undersigned (whose title is supplied below) is empowered to sign this certificate on behalf of the above-identified assignee.

Signature:

Paul W Davis

Date:

10/21/04

Name:

Paul W. Davis

Title:

Vice President of Intellectual Property Law  
Amkor Technology, Inc.



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Sung Soon Park, Sang Jae Jang, Choon Heung Lee,  
Seon Goo Lee, Eun Sook Sohn, Sung Su Park  
Assignee: Amkor Technology, Inc.  
Title: SEMICONDUCTOR PACKAGE STRUCTURE REDUCING WARPAGE  
AND MANUFACTURING METHOD THEREOF  
Serial No.: 10/672,886 Filed: September 26, 2003  
Examiner: Tuan H. Nguyen Group Art Unit: 2813  
Docket No.: GK0017

Monterey, CA  
October 28, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

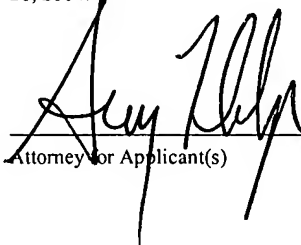
REQUEST FOR CHANGE OF ATTORNEY DOCKET NUMBER

Dear Sir:

Please change the Attorney Docket Number in the above application from "AMK-BK-00001" to "GK0017". Please use Attorney Docket Number "GK0017" in all future correspondence with Applicant's attorney.

**CERTIFICATE OF MAILING**

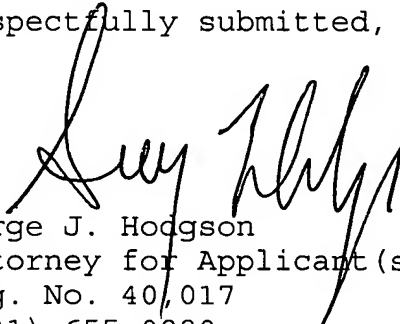
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 28, 2004.



Attorney for Applicant(s)

October 28, 2004  
Date of Signature

Respectfully submitted,



Serge J. Hodgson  
Attorney for Applicant(s)  
Reg. No. 40,017  
(831) 655-0880